

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A process for producing an electronic component, comprising:
forming a via hole in a base material having a conductor layer on at least one surface thereof by performing laser irradiation from the other surface side of the base material;
forming a conductor part in the via hole through deposition of plating in the via hole using the conductor layer as an electrode; and
causing an electroless plating to be deposited in the via hole such that an electroless plating layer in close contact with an inner wall surface of the via hole extends in the thickness direction of the conductor part.

Claim 2 (Currently Amended): A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a conductor layer formed on one surface thereof, the process comprising:

forming a via hole in the base material having the conductor layer by performing laser irradiation at least from the other surface side of the base material;
forming an electroless plating layer in close contact with an inner wall surface of the via hole and without contacting the core material after deposition of a plating until the core material exposed on the inner wall surface of the via hole is covered by using the conductor layer as an electrode; and
depositing a plating again by using the conductor layer as an electrode to cover the electroless plating layer to thereby form a conductor part in the via hole.

Claim 3 (Original): A process for producing an electronic component according to Claim 2, wherein the core material is caused to protrude from the inner wall surface of the via hole through laser irradiation to thereby form an anchor structure with respect to the conductor part.

Claim 4 (Original): A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a conductor layer formed on one surface thereof, the process comprising:

forming a via hole in the base material having the conductor layer by performing laser irradiation at least from the other surface side of the base material;

causing the core material to protrude from an inner wall surface of the via hole; and

depositing a plating by using the conductor layer as an electrode so as to form an anchor structure together with the core material protruding from the inner wall surface of the via hole to form a conductor part in the via hole.

Claim 5 (Original): A process for producing an electronic component according to any one of claims 2 through 4, wherein the core material is formed of glass cloth.

Claims 6-13 (Canceled).